

# SKM75GB12F4



## SEMITRANS® 2

### High Speed IGBT4 Modules

#### SKM75GB12F4

##### Target Data

##### Features

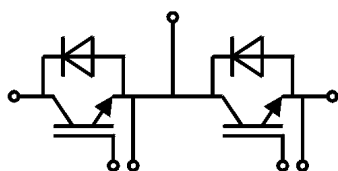
- High speed trench and field-stop IGBT
- CAL4 ultra-fast = soft switching 4. generation CAL-diode
- Insulated copper baseplate using DBC technology (Direct Bonded Copper)
- Increased power cycling capability
- For higher switching frequencies above 15kHz
- UL recognized, file no. E63532

##### Typical Applications\*

- UPS
- Electronic welders
- Inductive heating
- Switched mode power supplies

##### Remarks

- Case temperature limited to  $T_c = 125^\circ\text{C}$  max.
- Recommended  $T_{op} = -40 \dots +150^\circ\text{C}$
- Product reliability results valid for  $T_j = 150^\circ\text{C}$



GB

#### Absolute Maximum Ratings

Symbol	Conditions	Values	Unit	
<b>IGBT</b>				
$V_{CES}$	$T_j = 25^\circ\text{C}$	1200	V	
$I_c$	$T_j = 175^\circ\text{C}$	$T_c = 25^\circ\text{C}$	103	A
		$T_c = 80^\circ\text{C}$	79	A
$I_{Cnom}$		75	A	
$I_{CRM}$	$I_{CRM} = 3 \times I_{Cnom}$	225	A	
$V_{GES}$		-20 ... 20	V	
$t_{psc}$	$V_{CC} = 800\text{ V}$ $V_{GE} \leq 15\text{ V}$ $V_{CES} \leq 1200\text{ V}$	$T_j = 150^\circ\text{C}$	10	$\mu\text{s}$
$T_j$		-40 ... 175	$^\circ\text{C}$	
<b>Inverse diode</b>				
$V_{RRM}$	$T_j = 25^\circ\text{C}$	1200	V	
$I_F$	$T_j = 175^\circ\text{C}$	$T_c = 25^\circ\text{C}$	94	A
		$T_c = 80^\circ\text{C}$	69	A
$I_{Fnom}$		75	A	
$I_{FRM}$	$I_{FRM} = 2 \times I_{Fnom}$	150	A	
$I_{FSM}$	$t_p = 10\text{ ms}$ , $\sin 180^\circ$ , $T_j = 25^\circ\text{C}$	380	A	
$T_j$		-40 ... 175	$^\circ\text{C}$	
<b>Module</b>				
$I_{t(RMS)}$		200	A	
$T_{stg}$		-40 ... 125	$^\circ\text{C}$	
$V_{isol}$	AC sinus 50 Hz, $t = 1\text{ min}$	4000	V	

#### Characteristics

Symbol	Conditions	min.	typ.	max.	Unit
<b>IGBT</b>					
$V_{CE(sat)}$	$I_c = 75\text{ A}$ $V_{GE} = 15\text{ V}$ chipelevel	$T_j = 25^\circ\text{C}$	2.08	2.41	V
		$T_j = 150^\circ\text{C}$	2.60	2.93	V
$V_{CE0}$	chipelevel	$T_j = 25^\circ\text{C}$	1.10	1.28	V
		$T_j = 150^\circ\text{C}$	0.95	1.13	V
$r_{CE}$	$V_{GE} = 15\text{ V}$ chipelevel	$T_j = 25^\circ\text{C}$	13	15	$\text{m}\Omega$
		$T_j = 150^\circ\text{C}$	22	24	$\text{m}\Omega$
$V_{GE(th)}$	$V_{GE} = V_{CE}$ , $I_c = 2.6\text{ mA}$	5.2	5.8	6.4	V
$I_{CES}$	$V_{GE} = 0\text{ V}$ , $V_{CE} = 1200\text{ V}$ , $T_j = 25^\circ\text{C}$			1	$\text{mA}$
$C_{ies}$	$V_{CE} = 25\text{ V}$ $V_{GE} = 0\text{ V}$	$f = 1\text{ MHz}$	4.4		$\text{nF}$
$C_{oes}$		$f = 1\text{ MHz}$	0.29		$\text{nF}$
$C_{res}$		$f = 1\text{ MHz}$	0.24		$\text{nF}$
$Q_G$	$V_{GE} = -8\text{ V} \dots +15\text{ V}$		425		$\text{nC}$
$R_{Gint}$	$T_j = 25^\circ\text{C}$		10		$\Omega$
$t_{d(on)}$	$V_{CC} = 600\text{ V}$ $I_c = 75\text{ A}$	$T_j = 150^\circ\text{C}$	t.b.d.		$\text{ns}$
$t_r$	$V_{GE} = +15/-15\text{ V}$	$T_j = 150^\circ\text{C}$	t.b.d.		$\text{ns}$
$E_{on}$	$R_{Gon} = 2\ \Omega$	$T_j = 150^\circ\text{C}$	7		$\text{mJ}$
$t_{d(off)}$	$R_{Goff} = 2\ \Omega$	$T_j = 150^\circ\text{C}$	t.b.d.		$\text{ns}$
$t_f$		$T_j = 150^\circ\text{C}$	t.b.d.		$\text{ns}$
$E_{off}$		$T_j = 150^\circ\text{C}$	5		$\text{mJ}$
$R_{th(j-c)}$	per IGBT			0.38	$\text{K/W}$
$R_{th(c-s)}$	per IGBT ( $\lambda_{grease} = 0.81\text{ W}/(\text{m}^2\text{K})$ )		0.143		$\text{K/W}$

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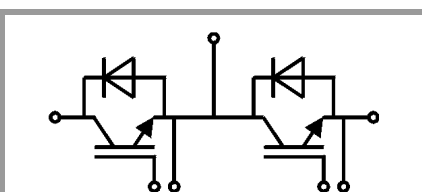
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Characteristics						
Symbol	Conditions		min.	typ.	max.	Unit
<b>Inverse diode</b>						
$V_F = V_{EC}$	$I_F = 75\text{ A}$ $V_{GE} = 0\text{ V}$ chipelevel	$T_j = 25^\circ\text{C}$		2.42	2.79	V
		$T_j = 150^\circ\text{C}$		2.34	2.69	V
$V_{F0}$	chipelevel	$T_j = 25^\circ\text{C}$		1.53	1.77	V
		$T_j = 150^\circ\text{C}$		1.12	1.36	V
$r_F$	chipelevel	$T_j = 25^\circ\text{C}$		12	14	m $\Omega$
		$T_j = 150^\circ\text{C}$		16	18	m $\Omega$
$I_{RRM}$	$I_F = 75\text{ A}$	$T_j = 150^\circ\text{C}$		t.b.d.		A
$Q_{rr}$	$V_{GE} = \pm 15\text{ V}$ $V_{CC} = 600\text{ V}$	$T_j = 150^\circ\text{C}$		t.b.d.		$\mu\text{C}$
$E_{rr}$		$T_j = 150^\circ\text{C}$		3		mJ
$R_{th(j-c)}$	per diode				0.58	K/W
$R_{th(c-s)}$	per diode ( $\lambda_{grease}=0.81\text{ W}/(\text{m}^2\text{K})$ )			0.144		K/W
<b>Module</b>						
$L_{CE}$				30		nH
$R_{CC+EE}$	measured per switch	$T_c = 25^\circ\text{C}$		0.65		m $\Omega$
		$T_c = 125^\circ\text{C}$		1.09		m $\Omega$
$R_{th(c-s)1}$	calculated without thermal coupling			0.036		K/W
$R_{th(c-s)2}$	including thermal coupling, $T_s$ underneath module ( $\lambda_{grease}=0.81\text{ W}/(\text{m}^2\text{K})$ )			0.057		K/W
$M_s$	to heat sink M6		3		5	Nm
$M_t$			2.5		5	Nm
	to terminals M5					Nm
$W$					160	g

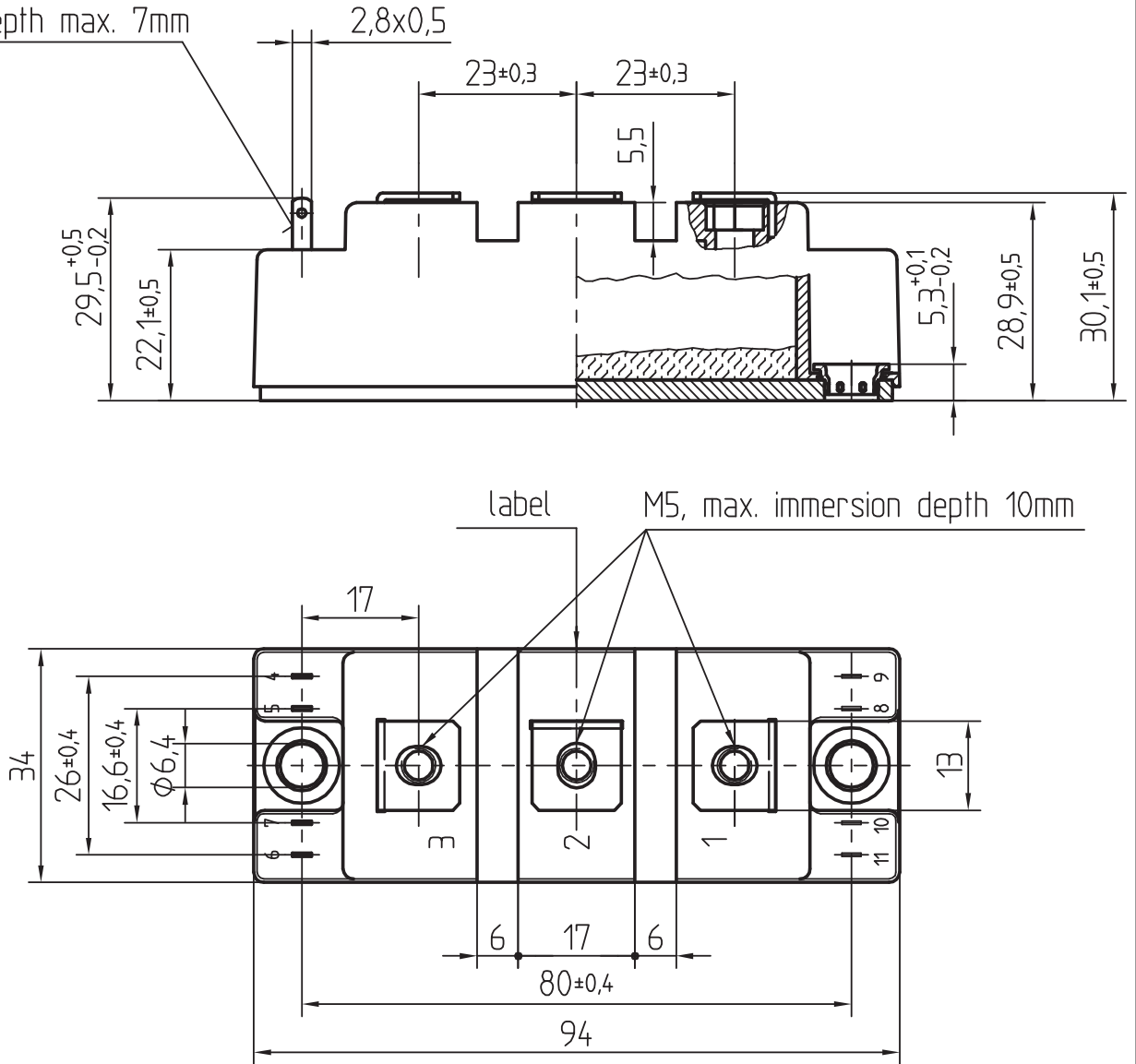


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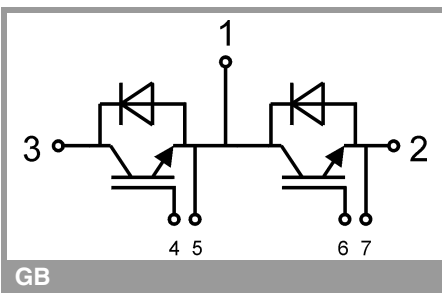
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Dimensions in mm

Plug in depth max. 7mm



General tolerance +/- 0,5 mm



This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, chapter IX.

## **\*IMPORTANT INFORMATION AND WARNINGS**

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